



Material Content Data Sheet



Sales Product Name		BSP297 H6327		Issued		19. July 2018			
MA#		MA001096074							
Package		PG-SOT223-4-21		Weight*		113.63 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	noble metal	gold	7440-57-5	0.078	0.07		684		
	non noble metal	tin	7440-31-5	0.020	0.02		176		
	inorganic material	silicon	7440-21-3	0.881	0.77	0.86	7749	8609	
leadframe	inorganic material	silicon	7440-21-3	0.010	0.01		89		
	non noble metal	titanium	7440-32-6	0.051	0.04		446		
	non noble metal	chromium	7440-47-3	0.152	0.13		1339		
	non noble metal	copper	7440-50-8	50.489	44.44	44.62	444318	446192	
wire	non noble metal	copper	7440-50-8	0.015	0.01	0.01	135	135	
encapsulation	organic material	carbon black	1333-86-4	0.600	0.53		5277		
	plastics	epoxy resin	-	8.994	7.92		79150		
	inorganic material	silicondioxide	60676-86-0	50.366	44.32	52.77	443238	527665	
leadfinish	non noble metal	tin	7440-31-5	1.464	1.29	1.29	12884	12884	
plating	noble metal	silver	7440-22-4	0.513	0.45	0.45	4515	4515	
*deviation	< 10%				Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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